A SENSOR AND METHOD FOR FABRICATING THE SAME

ABSTRACT

A sensor and method for fabricating a sensor is disclosed that in one embodiment bonds an etched semiconductor substrate wafer (300) to an etched device wafer (100) comprising a silicon on insulator wafer to create a suspended structure, the flexure of which is determined by an embedded sensing element (140) to measure absolute pressure. Interconnect channels (400) embedded in the sensor facilitate streamlined packaging of the device while accommodating interconnectivity with other devices.

Figure 1.